



SCOPE OF ACCREDITATION

Electronics

Ultra Electronics Limited
Waverley House Hampshire Road
Weymouth Dorset, DT4 9XD
United Kingdom

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: www.eAuditNet.com - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

AC7120 Rev C - Nadcap Audit Criteria for Circuit Card Assemblies (to be used on audits on/after 1 February 2015)

- 07– CAD/CAM Data
- 08– Electrostatic Discharge (ESD)
- 09– Material Handling
- 10– Moisture Sensitive Components and Materials
- 11– Re–Packaging
- 12.1– Programming: Component Programming (Prior Assembly)
- 12.2– Programming: Circuit Card Assembly Programming
- 13– Electronic Component Preparation For Preassembly Process
- 14– Stencil Printing
- 15.1– Part Placement: General
- 15.2– Part Placement: Manual
- 15.3– Part Placement: Operator–Assisted
- 15.4– Part Placement: Automated Part Placement
- 15.5– Part Placement: Build through / Build Short
- 15.6– Part Placement: Clinched Component Leads
- 16.1– In–Process Verification / Inspection: Visual
- 16.2– In–Process Verification / Inspection: AOI
- 16.3– In–Process Verification / Inspection: X–Ray
- 17– Bonding
- 18.1– Assembly Soldering Processes: General
- 18.2– Assembly Soldering Processes: Reflow Soldering
- 18.3– Assembly Soldering Processes: Wave Soldering

- 18.4– Assembly Soldering Processes: Selective Soldering
- 18.5– Assembly Soldering Processes: Hand Soldering
- 19.1– Secondary Assembly: Mechanical Part Installation
- 19.2– Secondary Assembly: Wire Cutting & Stripping
- 19.3– Secondary Assembly: Jumper Wire Installation
- 19.4– Secondary Assembly: Stranded Wire Tinning
- 19.5– Secondary Assembly: Compliant Pin (Press Fit) Connector Installation
- 20– Cleanliness
- 21– Coating and Encapsulation
- 22.1– Final Tests: Environmental Stress Screening
- 22.2– Final Tests: Bed of Nails Testing
- 22.3– Final Tests: Flying Probe Testing
- 22.4– Final Tests: Boundary Scan Testing
- 22.5– Final Tests: Manual Testing
- 22.6– Final Tests: Functional Testing
- 23– Final Inspection
- 24– Rework